

**Amendment to the Specification:**

Please replace the paragraph beginning at page 1, line 17, with the following rewritten paragraph:

-- The chip carrier 20 includes a plurality of input leads 202, each of which is connected to one of input terminals of the LSI chip 1, a plurality of output leads 203, each of which is connected to one of the output terminals OT001-OT384 of the LSI chip 1, a plurality of test pads 204, each of which is connected to one of the output leads 203, a single test signal input lead 21, which is connected to the test signal input terminal 12 of the LSI chip 1 for the test enable signal TEST EN and a ~~sibgle~~ single test signal output lead 22, which is connected to the test signal output terminal 13 of the LSI chip 1 for outputting the test result TEST EN. Although the test pads 204 are not required to achieve the invention, the test pads 204 would be useful at the evaluation of the LSI chip 1 before completion of the TFT source driver device. The reason for this is described later. --